	Product Wafer MSDS	Rev 3.0
		16.01.2024

MATERIAL SAFETY DATA SHEET

1.0 IDENTIFICATION

Product Name: (8") Silicon Wafer
General Use: Semiconductor Manufacturing
Product Description: Semiconductor Finished product

MANUFACTURE

Company Name: Tower Semiconductor LTD.
Address: POB 619 Migdal Haemek Israel 23105

Responsible Div: QA & Safety
Telephone: (972) 4-6506611
Fax: (972) 4-6047035
EMERGENCY TELEPHONE NUMBER: (972) 4-6506611


2.0 COMPOSITION / INFORMATION ON INGREDIENTS

Substances / Mixture : Mixture

Composition (Element)	CAS No.	Proportion (%)
Silicon (Si)	7440-21-3	99.60
Other minority Dopant		
Aluminum (Al)	7429-90-5	<0.25
Titanium (Ti)	7440-32-6	<0.04
Indium (In)	7440-74-6	<0.002
Tungsten (W)	7440-33-7	<0.08
Cobalt (Co)	7440-48-4	<0.002
Arsenic (As)	7440-38-2	<0.002
Copper	7440-50-8	<0.002
Boron	7440-42-8	<0.02
Phosphorus	7723-14-0	<0.002

3.0 HAZARDS IDENTIFICATION

Hazard effects
 Human health effects: Skin contact causes irritation.
 Environmental effects: NA
 Class name of hazard: NA

	Product Wafer MSDS	Rev 3.0
		16.01.2024

MATERIAL SAFETY DATA SHEET

4.0 FIRST AID MEASURES

Inhalation: NA
Eye: NA

5.0 FIRE FIGHTING MEASURES


Measures: Shut off fuel as much as possible.
Equipments: Dry chemical or carbon dioxide should be used for small fire.
Fire fighters should wear proper protective clothes.

6.0 ACCIDENTAL RELEASE MEASURES

Equip extinguishers in case of ignition.
Quickly shut off all ignition sources.

7.0 HANDLING AND STORAGE

Handling: Fragile-Handle with care.
Shut off all sources of ignition.
Storage: Keep away all sources of ignition.
Do not heat.
Store in well-ventilated area.
Keep dry.

	Product Wafer MSDS	Rev 3.0
		16.01.2024

MATERIAL SAFETY DATA SHEET

8.0 EXPOSURE CONTRROLS/PERSONAL PROTECTION

EXPOSURE LIMIT VALUES: NA
 EXPOSURE CONTROLS
 Engineering controls: NA
 Personal protection
 Respiratory protection: NA
 Eye protection: NA
 Skin protection

9.0 PHYSICAL AND CHEMICAL PROPERTIES


Appearance: Chip
 Color: various colors
 Boiling Point: Not Available
 Melting Point: - Not Available
 Density: - Not Available
 Vapor Pressure: - Not Available
 Vapor Density: - Not Available
 Solubility in water: Insoluble

10. STABILTY AND REACTIVITY

STABILITY: Stable
 MATERIALS TO AVOID

11. TOXICOLOGICAL INFORMATION

Acute toxicity
 Sensitization – N/A
 Chronic Toxicity - N/A
 Mutagen city - N/A
 Carcinogenicity - N/A
 IARC - N/A
 NTP - N/A
 OSHA - N/A
 Reproductive and

	Product Wafer MSDS	Rev 3.0
		16.01.2024

Developmental Toxicity - N/A
Other – N/A

MATERIAL SAFETY DATA SHEET

12. ECOLOGICAL INFORMATION

ECOTOXICITY -
PERSISTENCE AND
DEGRADABILITY -
BIOACCUMULATIVE
POTENTIAL –

13. DISPOSAL CONSIDERATION

Disposal method: All excess material must be collected and transferred to a Professional waste disposal company for treatment.
Carefully review information in **-7.HANDLING & STORAGE.**

Special control industrial Disposal

14.0 TRANSPORT INFORMATION

UN sorts – N/A
Domestic regulation – N/A
Special safety measurement
And condition

15.0 REGULATORY INFORMATION

N/A

16.0 OTHER INFORMATION

N/A